

# SCIENTIFIC REPORTS

## OPEN Publisher Correction: Morphology and mechanics of fungal mycelium

M. R. Islam<sup>1</sup>, G. Tudryn<sup>2</sup>, R. Bucinell<sup>3</sup>, L. Schadler<sup>4</sup> & R. C. Picu<sup>1</sup>

Correction to: *Scientific Reports* <https://doi.org/10.1038/s41598-017-13295-2>, published online 12 October 2017

The original PDF version of this Article contained errors. Figures 3, 4 and 7 were duplicated in Figures 4, 6 and 10 respectively, Figures 4–8 were incorrectly listed as Figures 5, 7, 8, 9 and 11 respectively and Figures 9–11 were missing.

These errors have now been corrected in the PDF version of this Article; the HTML version was correct from the time of publication.



**Open Access** This article is licensed under a Creative Commons Attribution 4.0 International License, which permits use, sharing, adaptation, distribution and reproduction in any medium or format, as long as you give appropriate credit to the original author(s) and the source, provide a link to the Creative Commons license, and indicate if changes were made. The images or other third party material in this article are included in the article's Creative Commons license, unless indicated otherwise in a credit line to the material. If material is not included in the article's Creative Commons license and your intended use is not permitted by statutory regulation or exceeds the permitted use, you will need to obtain permission directly from the copyright holder. To view a copy of this license, visit <http://creativecommons.org/licenses/by/4.0/>.

© The Author(s) 2018

<sup>1</sup>Department of Mechanical, Aerospace and Nuclear Engineering, Rensselaer Polytechnic Institute, Troy, NY, 12180, USA. <sup>2</sup>Ecovative Design LLC, Green Island, NY, 12183, USA. <sup>3</sup>Department of Mechanical Engineering, Union College, Schenectady, NY, 12308, USA. <sup>4</sup>Department of Material Science and Engineering, Rensselaer Polytechnic Institute, Troy, NY, 12180, USA. Correspondence and requests for materials should be addressed to R.C.P. (email: [picuc@rpi.edu](mailto:picuc@rpi.edu))